



APPENDIX

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Please amend claim 1 as follows:

1 1. (Amended) A bond pad assembly comprising:
2 a bond pad;
3 a trace that applies an attractive force to solder placed on the pad,
4 said trace coupled to said pad and extending away from said pad in a first
5 direction; and
6 a trace stub to counteract the attractive force applied by the trace,
7 said trace stub coupled to said pad and extending away from said pad in a
8 direction other than said first direction.

1 10. (Amended) A bonding system comprising:
2 a bond pad;
3 a trace coupled to said bond pad and extending away from said
4 pad; and
5 an element adapted to counteract [the] an attractive [forces] force
6 applied by the trace to solder placed on the bond pad.

1 16. (Amended) The system of claim 10 wherein the attractive [forces]
2 force applied by the trace to said solder [ball arise] arises from [the configuration
3 of] said trace being coupled to and extending away from said bond pad, said
4 element adapted to emulate said trace.